IN THE CLAIMS:

The status of the claims are as follows:

Claims 1-5. (Cancelled)

6. (Original) An apparatus for depositing flux on a semiconductor chip, the apparatus comprising:

a support for positioning the semiconductor chip at a predetermined location for depositing flux, the semiconductor chip having a plurality of flip-chip bumps arranged on its surface; and

a jet printing head for printing a flux pattern, on the flip-chip bumps, the flux pattern substantially identical to an arrangement pattern of the plurality of flip-chip bumps on the semiconductor chip, such that the flux is deposited substantially only on the flip-chip bumps.

7. (Allowed) An apparatus for depositing flux on a semiconductor chip, the apparatus comprising:

a support for positioning the semiconductor chip at a predetermined location for depositing flux, the semiconductor chip having a plurality of flip-chip bumps arranged on its surface; and

a jet printing head for printing a flux pattern, on the flip-chip bumps, the flux pattern substantially identical to an arrangement pattern of the plurality of flip-chip bumps on the semiconductor chip, such that the flux is deposited substantially only on the

flip-chip bumps further comprising data storage storing an arrangement pattern of the flip-chip bumps on the semiconductor chip.

8. (Allowed) The apparatus of claim 7, wherein the arrangement pattern is stored in computer-recognizable data in the data storage.

9. (Allowed) The apparatus of claim 8, wherein the jet printing head prints the flux pattern based on the computer-recognizable data stored in the data storage.

10. (Allowed) The apparatus of claim 7, wherein the jet printing head is capable of printing a plurality of flux patterns corresponding to a plurality of arrangement patterns of flip-chip bumps of semiconductor chips by storing the plurality of arrangement patterns in the data storage.

11. (Original) The apparatus of claim 6, wherein the support is a conveying plate transporting the semiconductor chip to the predetermined location for printing the pattern on the flip-chip bumps.

12. (Original) The apparatus of claim 11, wherein the conveying plate transports a plurality of semiconductor chips successively arranged thereon to the predetermined location for printing the pattern.

13. (Allowed) The apparatus of claim 7, wherein the support is a conveying plate transporting the semiconductor chip to the predetermined location for printing the pattern on the flip-chip bumps.

14. (Allowed) The apparatus of claim 13, wherein the conveying plate transports a plurality of semiconductor chips successively arranged thereon to the predetermined location for printing the pattern.